

A2

Detailed Description--.

On page 5, delete line 1, and insert:
--What Is Claimed Is--.

IN THE ABSTRACT:

Please amend the abstract as follows:

Delete line 1, and insert:

--Abstract Of The Disclosure--.

Delete line 3, and insert --A temperature sensor includes--.

Line 5, after "and" insert --evaluated. The--.

Delete lines 6-7.

Line 8, delete "The" and "(14)".

Line 9, delete "(24)".

Delete line 12.

IN THE CLAIMS:

Please cancel claims 1-8, without prejudice.

Please add the following new claims:

- 5w3
B1
A2
9. (New) A temperature sensor comprising:
a carrier having a surface composed of at least one of a metal oxide,
a metal carbide and a metal nitride; and

Sub B1 Contd

at least one conductor track composed of a metal, the at least one conductor track covering the surface of the carrier, a temperature-dependent change in a resistance of the at least one conductor track being measured and evaluated.

10. (New) The temperature sensor according to claim 9, wherein the corner is composed of at least one of zirconium dioxide and aluminum oxide.

11. (New) The temperature sensor according to claim 9, wherein the at least one conductor track is composed of one of cobalt, nickel, copper and platinum.

12. (New) The temperature sensor according to claim 9, wherein an a.c. voltage is applied to the at least one conductor track to determine the resistance.

13. (New) The temperature sensor according to claim 9, wherein the temperature sensor is situated in a layer of a laminated layer sensor.

14. (New) A method for manufacturing a temperature sensor comprising the step of:

A3 Sub B2

forming at least one conductor track by a currentless deposition of a metal onto a surface of a carrier and by a subsequent thermal treatment, the carrier being composed of at least one of a metal oxide, a metal nitride and a metal carbide, a temperature-dependent change in a resistance of the at least one conductor track being measured and evaluated by the temperature sensor.

Sub D1 Contd

15. (New) The method according to claim 14, wherein a layer thickness of a metal layer situated on the surface of the carrier is determined by at least one of a duration and a selected temperature during a thermal treatment.

16. (New) The method according to claim 14, wherein the carrier is used as a powder.